### 5.0mm x 6.0mm SURFACE MOUNT LED LAMP



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

#### Features

- Chips can be controlled separately.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

#### Part Number: KAAF-5060QBDSURKZGCT

Blue Hyper Red Green

#### Description

The Blue source color devices are made with InGaN Light Emitting Diode.

The Hyper Red source color devices are made with Al-

GaInP on GaAs substrate Light Emitting Diode.

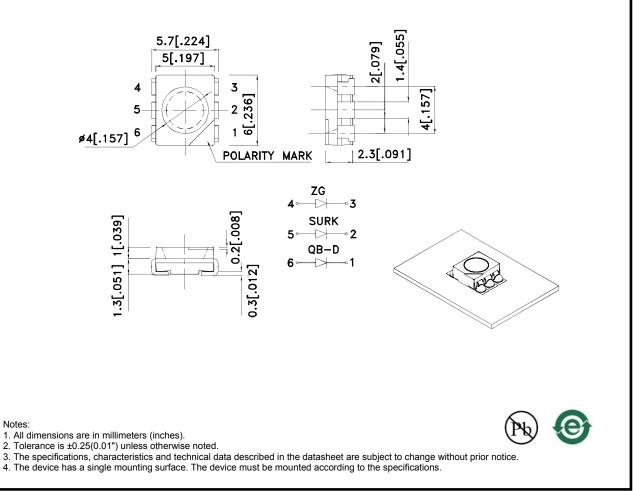
The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.





SPEC NO: DSAK6945 APPROVED: WYNEC REV NO: V.1 CHECKED: Allen Liu DATE: APR/27/2010 DRAWN: SHANW PAGE: 1 OF 7 ERP: 1201006418

Selection Guide Part No.	Dice	Lens Type	Iv (mcd) [2] @ 30mA		Viewing Angle [1]
			Min.	Тур.	201/2
KAAF-5060QBDSURKZGCT	Blue (InGaN)	WATER CLEAR	110	250	100°
	Hyper Red (AlGaInP)		180	350	
	Green (InGaN)		280	650	

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25 C								
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions		
λpeak	Peak Wavelength	Blue Hyper Red Green	468 650 515		nm	I⊧=20mA		
λD [1]	Dominant Wavelength	Blue Hyper Red Green	470 630 525		nm	I⊧=20mA		
Δλ1/2	Spectral Line Half-width	Blue Hyper Red Green	25 28 30		nm	I⊧=20mA		
С	Capacitance	Blue Hyper Red Green	100 35 45		pF	VF=0V;f=1MHz		
Vf [2]	Forward Voltage	Blue Hyper Red Green	3.3 1.95 3.3	4 2.5 4.1	V	I⊧=20mA		
lr	Reverse Current	Blue Hyper Red Green		50 10 50	uA	VR=5V		

#### Electrical / Optical Characteristics at TA=25°C

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

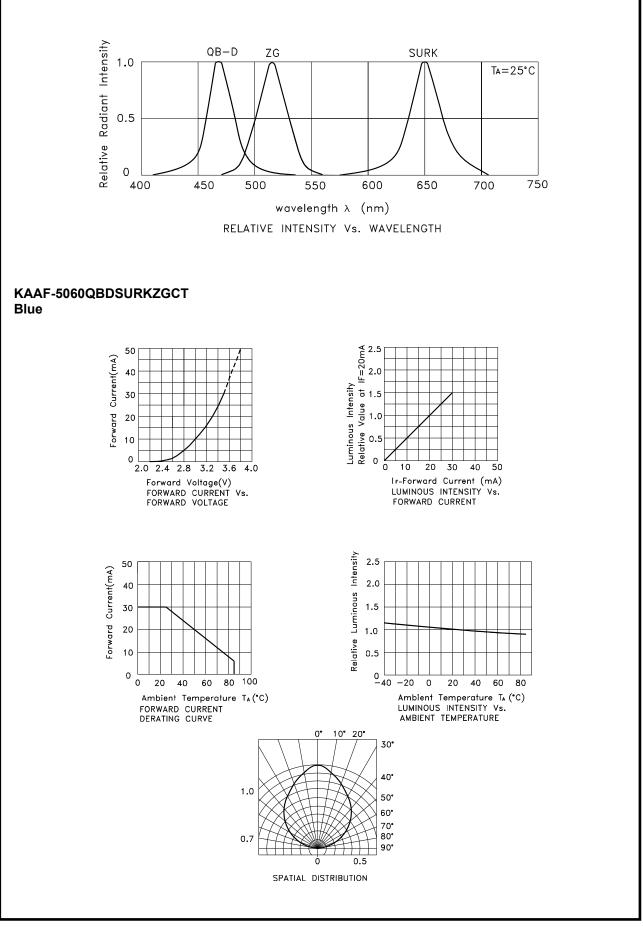
### Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Hyper Red	Green	Units			
Power dissipation[2]		mW					
DC Forward Current	30	30	30	mA			
Peak Forward Current [1]	150	185	150	mA			
Reverse Voltage		V					
Operating Temperature	-40°C To +85°C						
Storage Temperature	-40°C To +85°C						

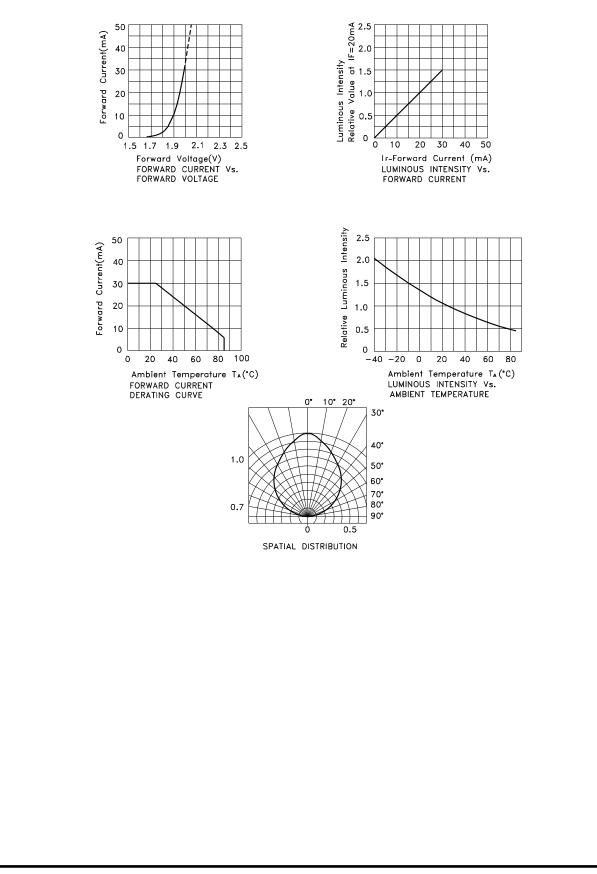
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

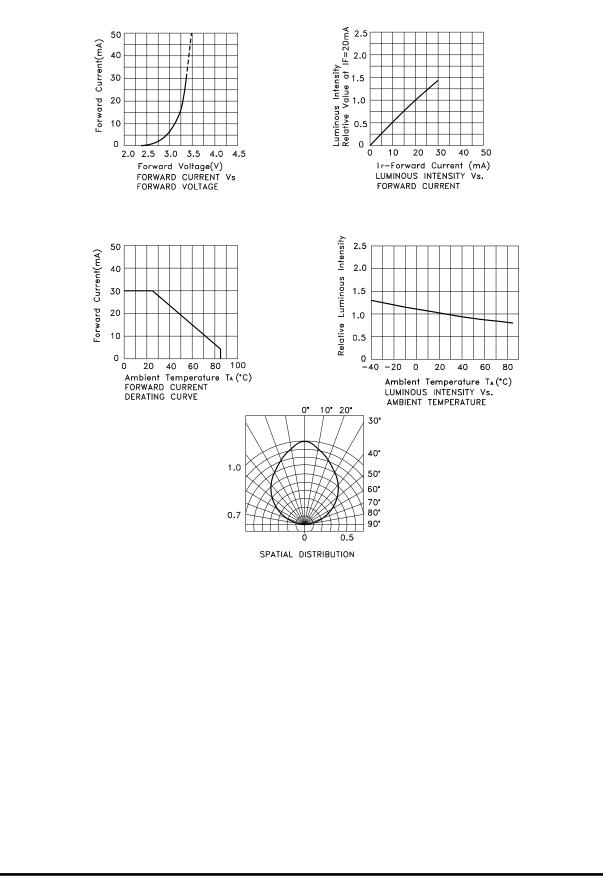
2. Within 350mW at all chips are lightened.



### Hyper Red



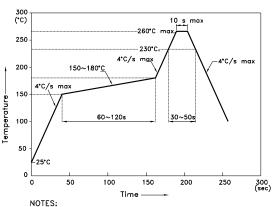
### Green



### KAAF-5060QBDSURKZGCT

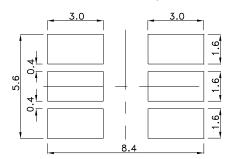
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

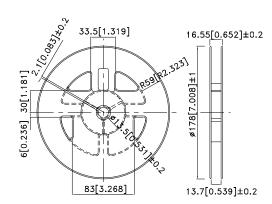


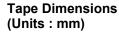
NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

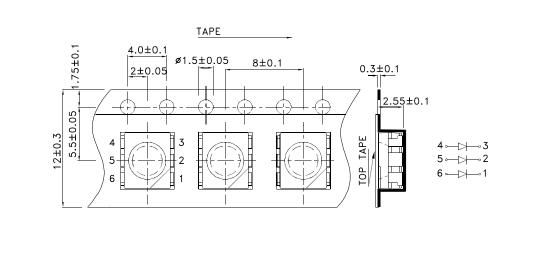
**Recommended Soldering Pattern** (Units : mm; Tolerance: ± 0.1)



### **Reel Dimension**







DATE: APR/27/2010 **DRAWN: SHANW** 

